

# TLP109

Programmable Controllers  
Industrial Inverters  
Switching Power Supplies

The Toshiba TLP109 mini-flat coupler is a small-outline coupler suitable for surface-mount assembly. The TLP109 consists of a high-output-power infrared LED optically coupled to a high-speed photodiode-transistor chip. The TLP109 is housed in the SO6 package and guarantees a creepage distance of  $\geq 5.0$  mm, a clearance of  $\geq 5.0$  mm and an insulation thickness of  $\geq 0.4$  mm. Therefore, the TLP109 meets the reinforced insulation class requirements of international safety standards.

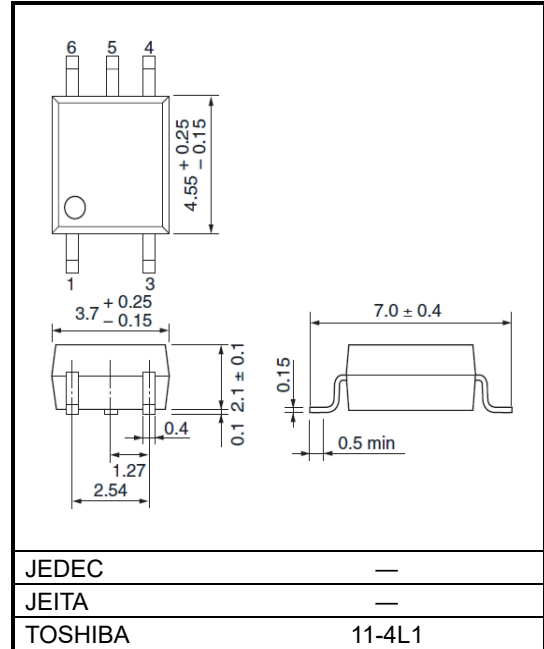
- Isolation voltage: 3750 Vrms (min)
- Switching speed:  $t_{pHL} = 0.8 \mu s$ ,  $t_{pLH} = 0.8 \mu s$  (max)  
@ $R_L = 1.9 k\Omega$
- TTL-compatible
- UL-recognized : UL 1577, File No.E67349
- cUL-recognized : CSA Component Acceptance Service No.5A  
File No.E67349
- VDE-approved: EN 60747-5-5, EN 62368-1 (Note 1)
- CQC-approved: GB4943.1, GB8898 Thailand Factory



仅适用于海拔 2000m 以下地区安全使用

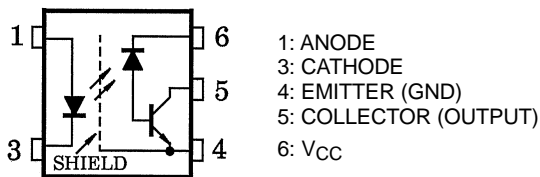
Note 1 : When a VDE approved type is needed, please designate the **Option(V4)**.

Unit: mm

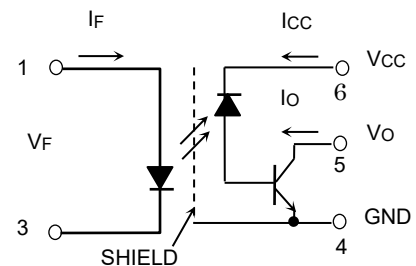


Weight: 0.08 g (typ.)

## Pin Configuration (Top View)



## Schematic



## Construction Mechanical Ratings

Creepage distance:	5.0 mm (min)
Clearance:	5.0 mm (min)
Insulation thickness:	0.4 mm (min)

Start of commercial production  
2008-07

## Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
LED	Forward current	I <sub>F</sub>	20	mA
	Forward Current Derating (Ta ≥ 95 °C)	Δ I <sub>F</sub> /°C	-0.36	mA/°C
	Pulse forward current (Note 1)	I <sub>FP</sub>	40	mA
	Peak transient forward current (Note 2)	I <sub>FPT</sub>	1	A
	Reverse voltage	V <sub>R</sub>	5	V
	Power dissipation (Note 3)	P <sub>D</sub>	40	mW
Detector	Output current	I <sub>O</sub>	8	mA
	Output Current Derating (Ta ≥ 95 °C)	Δ I <sub>O</sub> /°C	-0.3	mA/°C
	Peak output current	I <sub>OP</sub>	16	mA
	Supply voltage	V <sub>CC</sub>	-0.5 to 30	V
	Output voltage	V <sub>O</sub>	-0.5 to 20	V
	Output power dissipation (Note 4)	P <sub>O</sub>	100	mW
Operating temperature range		T <sub>opr</sub>	-55 to 125	°C
Storage temperature range		T <sub>stg</sub>	-55 to 125	°C
Lead solder temperature (10 s)		T <sub>sol</sub>	260	°C
Isolation Voltage (R.H. ≤ 60 %, AC 60 s) (Note 5)		BVS	3750	V <sub>rms</sub>

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook (“Handling Precautions”/“Derating Concept and Methods”) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: 50 % duty cycle, 1 ms pulse width. Derate 0.72 mA / °C above 95 °C.

Note 2: Pulse width ≤ 1 μs, 300 pps.

Note 3: Derate 0.72 mW / °C above 95 °C.

Note 4: Derate 1.8 mW / °C above 95 °C.

Note 5: Device considered a two-terminal device: Pins 1 and 3 shorted together, and pins 4, 5 and 6 shorted together.

### Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
LED	Forward voltage	$V_F$	$I_F = 16 \text{ mA}$	1.50	1.64	1.85	V
	Forward voltage temperature coefficient	$\Delta V_F / \Delta T_a$	$I_F = 16 \text{ mA}$	—	-1.6	—	mV / °C
	Reverse current	$I_R$	$V_R = 3 \text{ V}$	—	—	10	$\mu\text{A}$
	Capacitance between terminals	$C_T$	$V_F = 0 \text{ V}, f = 1 \text{ MHz}$	—	60	—	pF
Detector	High level output current	$I_{OH} (1)$	$I_F = 0 \text{ mA}, V_{CC} = V_O = 5.5 \text{ V}$	—	3	500	nA
		$I_{OH} (2)$	$I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}$ $V_O = 20 \text{ V}$	—	—	5	$\mu\text{A}$
		$I_{OH}$	$I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}$ $V_O = 20 \text{ V}, T_a = 100 \text{ }^\circ\text{C}$	—	—	50	
	High level supply current	$I_{CCH}$	$I_F = 0 \text{ mA}, V_{CC} = 30 \text{ V}$	—	0.01	1	$\mu\text{A}$
Current transfer ratio	$I_O / I_F$	$I_F = 16 \text{ mA}, V_{CC} = 4.5 \text{ V}$ $V_O = 0.4 \text{ V}$	20	—	—	%	
Low level output voltage	$V_{OL}$	$I_F = 16 \text{ mA}, V_{CC} = 4.5 \text{ V}$ $I_O = 2.4 \text{ mA}$	—	—	0.4	V	

### Isolation Characteristics (Ta = 25°C)

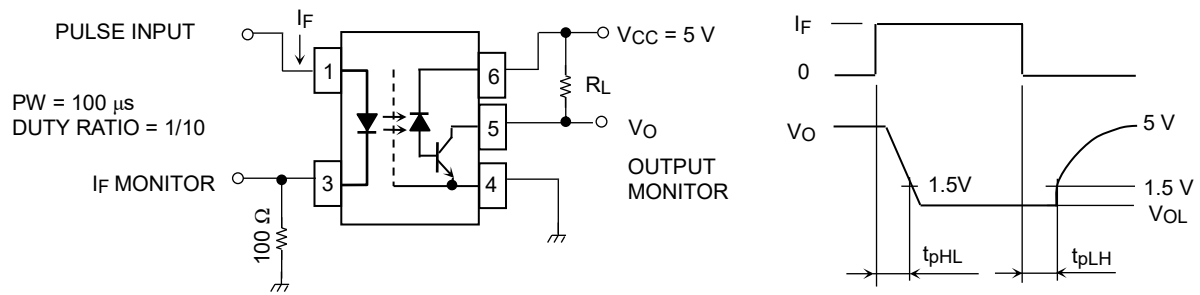
Characteristic	Symbol	Test Conditions	Min	Typ.	Max	Unit
Capacitance input to output	$C_S$	$V = 0 \text{ V}, f = 1 \text{ MHz}$ (Note 5)	—	0.8	—	pF
Isolation resistance	$R_S$	R.H. $\leq 60 \%$ , $V_S = 500 \text{ V}$ (Note 5)	$10^{12}$	$10^{14}$	—	$\Omega$
Isolation voltage	$B_{VS}$	AC, 60 s (Note 5)	3750	—	—	$V_{rms}$

### Switching Characteristics (Ta = 25°C, Vcc = 5 V)

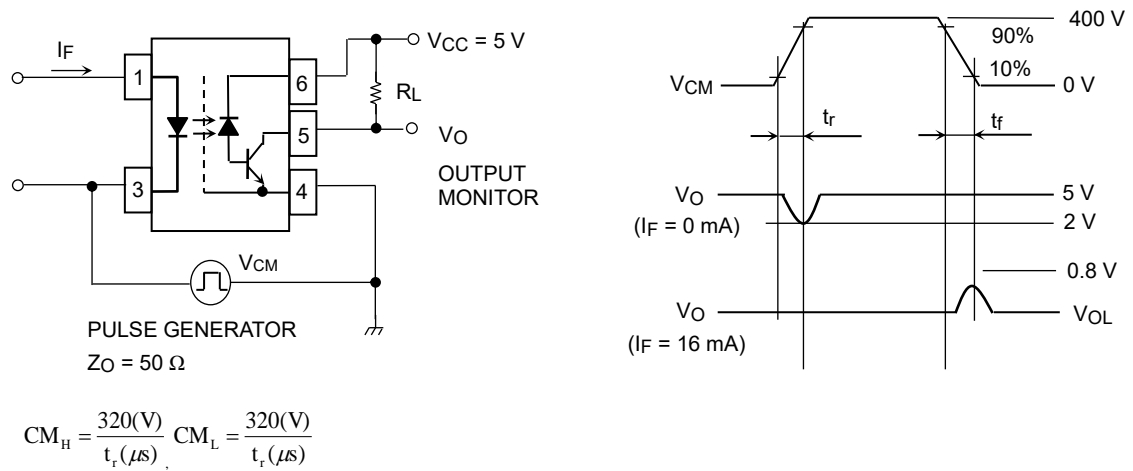
Characteristic	Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Propagation delay time (H → L)	$t_{pHL}$	Figure 1	$I_F = 0 \rightarrow 16 \text{ mA}$ $R_L = 1.9 \text{ k}\Omega$	—	—	0.8	$\mu\text{s}$
Propagation delay time (L → H)	$t_{pLH}$		$I_F = 16 \rightarrow 0 \text{ mA}$ $R_L = 1.9 \text{ k}\Omega$	—	—	0.8	$\mu\text{s}$
Common mode transient immunity at high output level (Note 6)	$CM_H$	Figure 2	$I_F = 0 \text{ mA}, V_{CM} = 400 \text{ V}_{p-p}$ $R_L = 4.1 \text{ k}\Omega$	5000	10000	—	V / $\mu\text{s}$
Common mode transient immunity at low output level (Note 6)	$CM_L$		$I_F = 16 \text{ mA}, V_{CM} = 400 \text{ V}_{p-p}$ $R_L = 4.1 \text{ k}\Omega$	-5000	-10000	—	V / $\mu\text{s}$

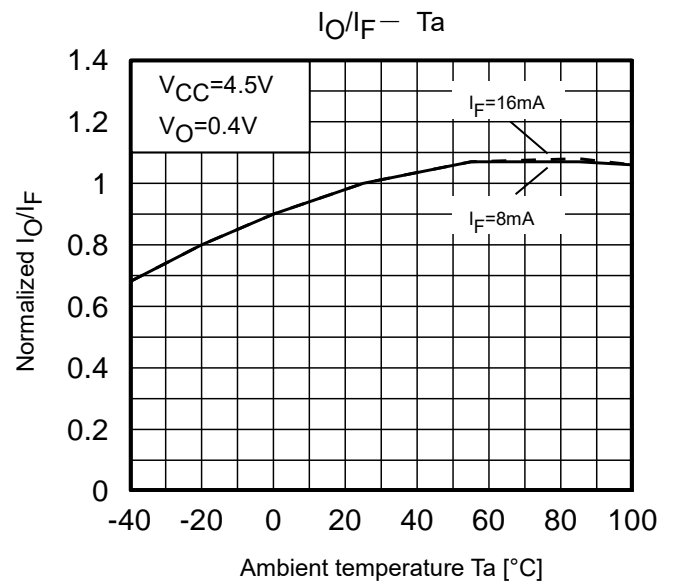
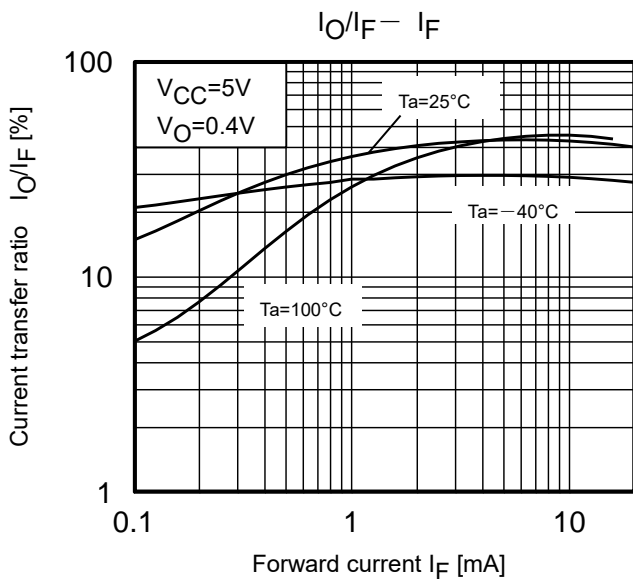
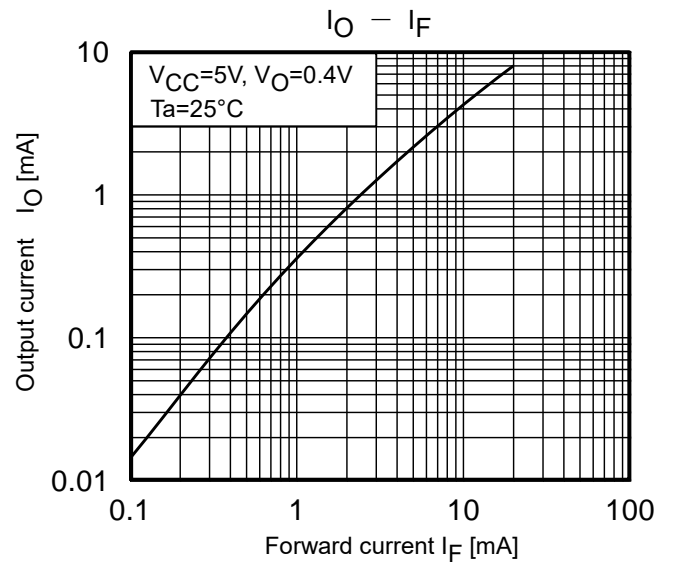
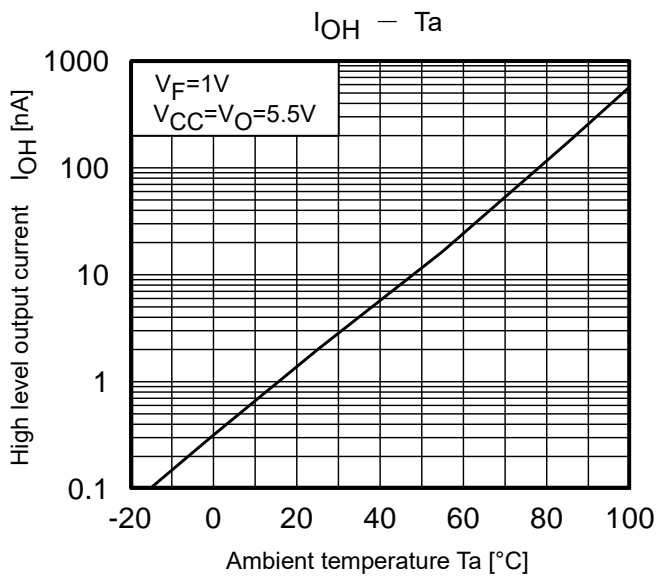
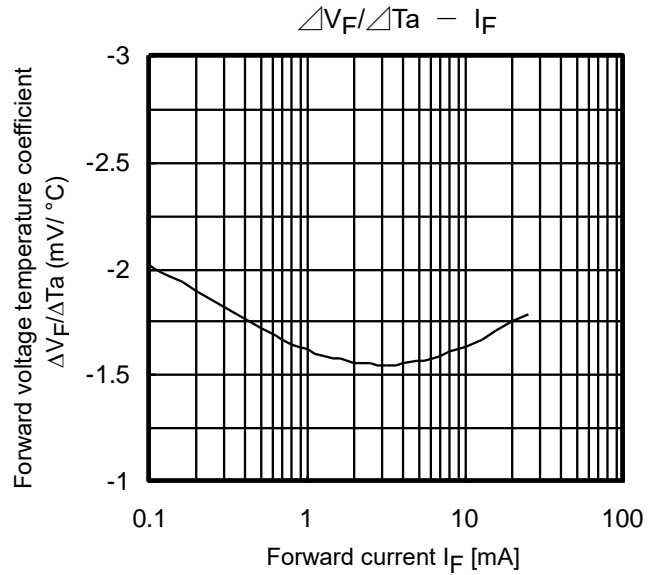
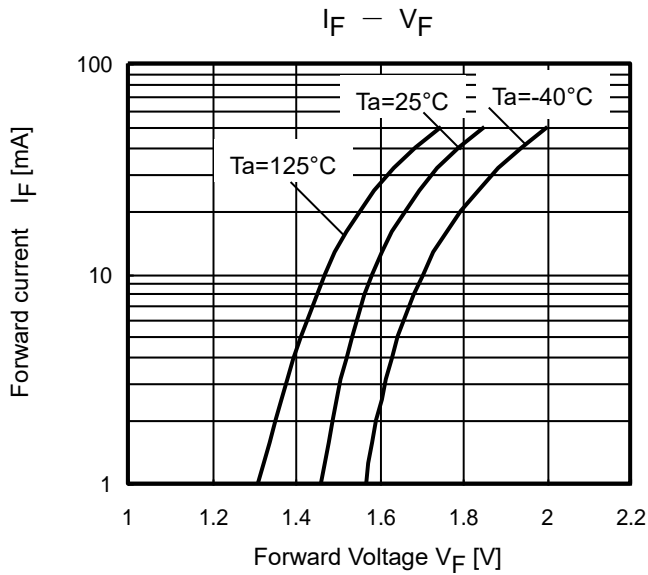
Note 6:  $CM_L$  is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic low state ( $V_O < 0.8 \text{ V}$ ).  
 $CM_H$  is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic high state ( $V_O > 2.0 \text{ V}$ )

**Figure 1: Switching Time Test Circuit and Waveform**

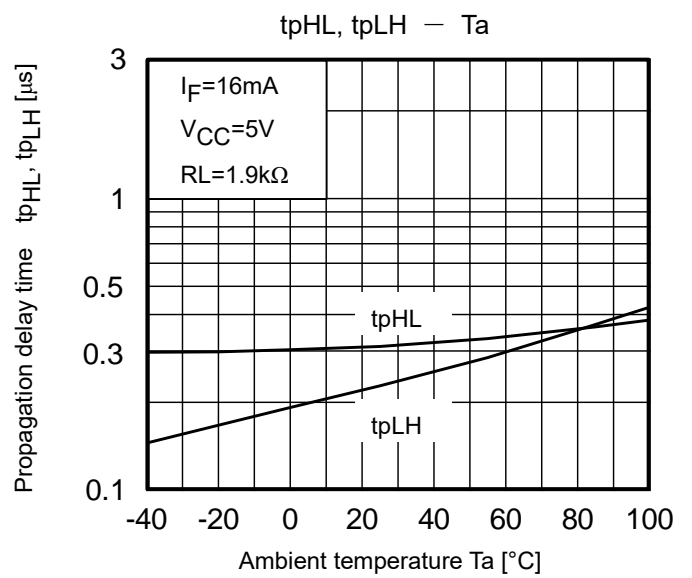
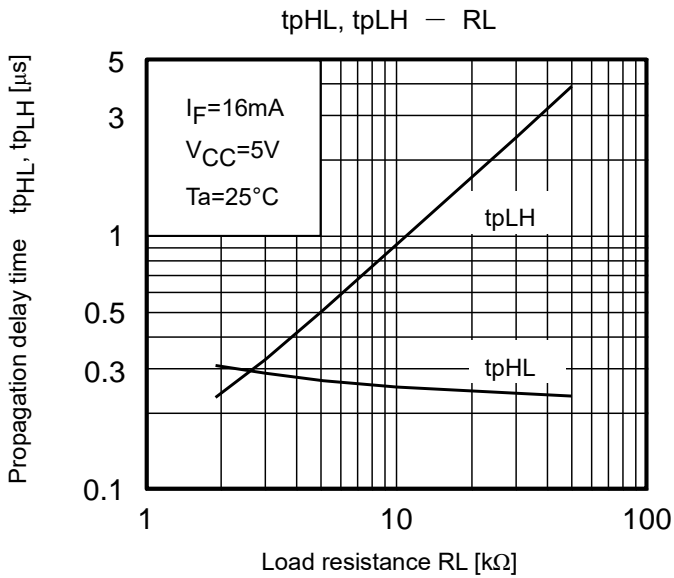
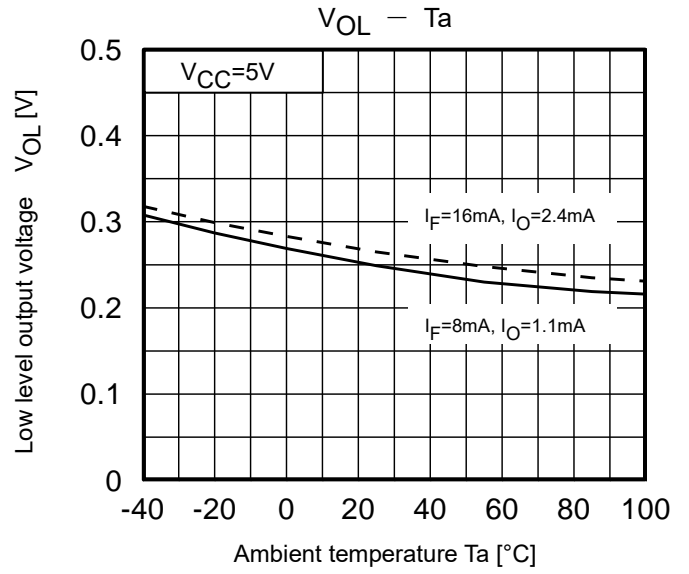
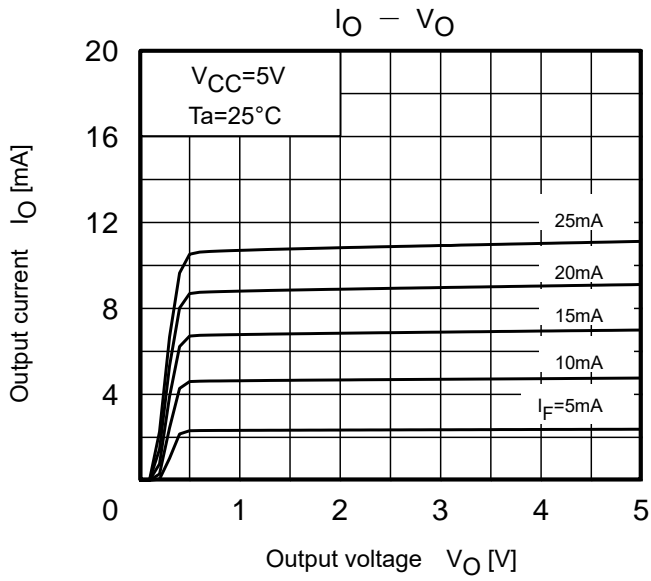


**Figure 2: Common Mode Transient Immunity Test Circuit and Waveform**





NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



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## PRECAUTIONS OF SURFACE MOUNTING TYPE PHOTOCOUPLER SOLDERING & GENERAL STORAGE

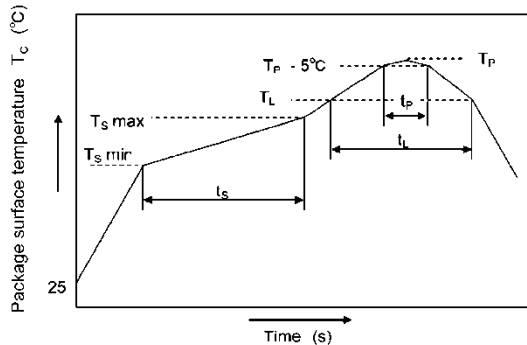
### (1) Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

#### 1) When Using Soldering Reflow

An example of a temperature profile when lead (Pb)-free solder is used

- The soldering temperature profile is based on the package surface temperature  
(See the figure shown below, which is based on the package surface temperature.)



	Symbol	Min	Max	Unit
Preheat temperature	$T_s$	150	200	°C
Preheat time	$t_s$	60	120	s
Ramp-up rate ( $T_L$ to $T_P$ )			3	°C/s
Liquidus temperature	$T_L$	217		°C
Time above $T_L$	$t_L$	60	150	s
Peak temperature	$T_P$		260	°C
Time during which $T_c$ is between ( $T_P - 5$ ) and $T_P$	$t_p$		30	s
Ramp-down rate ( $T_P$ to $T_L$ )			6	°C/s

- Reflow soldering must be performed once or twice.
- The mounting should be completed with the interval from the first to the last mountings being 2 weeks.

#### 2) When using soldering Flow

- Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.
- Mounting condition of 260 °C within 10 seconds is recommended.
- Flow soldering must be performed once.

#### 3) When using soldering Iron

- Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C.
- Heating by soldering iron must be only once per 1 lead.

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